L Number	Hits	Search Text	DB	Time stamp
12	2	4821152.pn.	USPAT; US-PGPUB;	2004/10/07 09:59
95	8714	winding with copper	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/10/07 11:40
96	1715	winding near copper	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/10/07 11:40
97	1715	winding near copper and py@<1980	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/10/07
98	182	winding near copper and @py<1980	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/10/07
99	. 11	winding near copper and @py<1980 and 361/\$	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/10/07
100	3	winding near copper same bifilar and @py<1980	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/10/07
101	20	winding near copper adj wire and @py<1980	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/07 11:47
102	1	winding near copper adj wire same limiter	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/10/07 11:48
103	2	winding near copper adj wire same limiting	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/10/07 11:49
104	413	winding near copper adj wire	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/07 11:49
105	1	winding near copper adj wire same bifilar	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/10/07
106	4	winding near2 copper adj wire same bifilar	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/07 11:51

107	354	winding near2 copper adj wire with coil	USPAT;	2004/10/07
			US-PGPUB;	11:51
			EPO; JPO;	
			DERWENT;	
108	3	winding near2 copper adj wire with coil	IBM_TDB USPAT;	2004/10/07
100	1	same bifilar	US-PGPUB;	11:51
		Same Billar	EPO; JPO;	11.31
			DERWENT;	1
			IBM TDB	
109	3	winding near2 copper adj wire with coil	USPAT;	2004/10/07
		and bifilar	US-PGPUB;	11:51
		·	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
110	45	copper adj wire with coil and bifilar	USPAT;	2004/10/07
			US-PGPUB; EPO; JPO;	11:58
			DERWENT;	
			IBM TDB	
113	34	copper adj wire with coil and bifilar	USPAT	2004/10/07
		sepport and many many many many		11:59
116	1	aluminum same copper adj wire with coil	USPAT	2004/10/07
		and bifilar		12:00
117	203	aluminum same copper adj wire with coil	USPAT	2004/10/07
				12:00
118	85	aluminum same copper adj wire with coil	USPAT	2004/10/07
		and @py<1990		12:04
119	1	aluminum same copper adj wire with coil	USPAT	2004/10/07
120	24	and bifilar	HCDAM	12:04
120	34	copper adj wire with coil and bifilar	USPAT	2004/10/07
1_	2	"20040047105"	USPAT;	2004/09/29
-	-	20010047103	US-PGPUB;	10:31
†			EPO; JPO;	10.31
			DERWENT;	
		, _	IBM TDB	
- - · -	1	inrush same current same bifilar same	USPAT;	2004/09/29
		winding	US-PGPUB;	14:45
			EPO; JPO;	
]		DERWENT;	
_	1		IBM_TDB	2004/09/29
-	1	inrush same bifilar same winding	USPAT; US-PGPUB;	14:45
			EPO; JPO;	T.2.40
			DERWENT;	
	1		IBM TDB	
_	22	protection same bifilar same winding	USPAT;	2004/09/29
			US-PGPUB;	11:43
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0004/00/00
-	265	inductance same bifilar same winding	USPAT;	2004/09/29
			US-PGPUB; EPO; JPO;	11:44
			DERWENT;	
			IBM TDB	
_	144	inductance with bifilar with winding	USPAT;	2004/09/29
		The state of the s	US-PGPUB;	11:44
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	. 4	inductance with bifilar with winding with	USPĀT;	2004/09/29
		resistance	US-PGPUB;	11:48
			EPO; JPO;	
		a a	DERWENT;	
1	1	I	IBM_TDB	1

			·····	
-	0	inductance with bifilar with winding with	USPAT;	2004/09/29
		inrush	US-PGPUB;	11:47
			EPO; JPO;	
		•	DERWENT;	
	•	2.4.6.12 - 1 1.4.2 1.4.2 1.4.2 1	IBM_TDB	2004/00/00
-	0	bifilar with winding with inrush	USPAT;	2004/09/29
			US-PGPUB;	11:47
			EPO; JPO;	
			DERWENT;	
		<u></u>	IBM_TDB	
-	70	bifilar with winding with resistance	USPAT;	2004/09/29
			US-PGPUB;	11:48
			EPO; JPO;	
			DERWENT;	
	•		IBM_TDB	2004/00/00
	0	bifilar with winding with resistance same	USPAT;	2004/09/29
		inrush	US-PGPUB;	11:48
			EPO; JPO;	
			DERWENT;	
[']		, ,	IBM_TDB	0004/00/55
-	612	resistance same inrush	USPAT;	2004/09/29
			US-PGPUB;	11:48
1 .1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	256	resistance same inrush same limit\$3	USPAT;	2004/09/29
			US-PGPUB;	11:50
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	49	resistance same inrush same limit\$3 same	USPAT;	2004/09/29
		AC	US-PGPUB;	11:51
1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	22	resistance with inrush same limit\$3 same	USPAT;	2004/09/29
_		<u>AC </u>	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	
-	5	("4328459" "4504898" "4678984"	USPAT	2004/09/29
	0.0	"5619127" "5715154").PN.		11:53
-	20	resistance with inrush with limit\$3 same	USPAT;	2004/09/29
.		AC	US-PGPUB;	12:55
			EPO; JPO;	
			DERWENT;	
	^	20020102047 11001	IBM_TDB	2004/00/00
-	0	20030102947.URPN.	USPAT	2004/09/29
_	2	6166610 nn	HCD2m.	11:59
-	2	6166619.pn.	USPAT;	2004/09/29
			US-PGPUB;	12:35
			EPO; JPO;	
			DERWENT;	
	2	5072504 mm	IBM_TDB	2004/00/00
-	2	5973584.pn.	USPAT;	2004/09/29
			US-PGPUB;	12:40
			EPO; JPO;	
	i		DERWENT;	
	,	٩٠ ١١١١٥٥٥	IBM_TDB	2004/00/20
-	1	de-20119996-\$.did.	USPAT;	2004/09/29
			US-PGPUB;	12:40
			EPO; JPO;	
. [DERWENT;	
	245		IBM_TDB	2004/00/00
-	345	resistance same mounting same soldering	USPAT;	2004/09/29
		same board	US-PGPUB;	13:16
1			EPO; JPO;	1
			DEDERMAN -	
			DERWENT; IBM TDB	

_	89	resistance with mounting with soldering with board	USPAT; US-PGPUB;	2004/09/29 13:16
			EPO; JPO; DERWENT; IBM TDB	
_	3	resistance with mounting with soldering	USPAT;	2004/09/29
		with board with pin	US-PGPUB;	13:18
			EPO; JPO;	
			DERWENT; IBM TDB	
_	13	resistance with mounting with soldering	USPAT;	2004/09/29
		with pin	US-PGPUB;	13:19
			EPO; JPO; DERWENT;	
			IBM TDB	
-	354	resistance with mounting with pin	USPĀT;	2004/09/29
			US-PGPUB;	13:20
			EPO; JPO; DERWENT;	
			IBM TDB	
_	20	,	USPAT;	2004/09/29
		solder\$3	US-PGPUB; EPO; JPO;	13:24
			DERWENT;	
			IBM_TDB	
-	138	+	USPAT;	2004/09/29
		solder\$3	US-PGPUB; EPO; JPO;	13:28
			DERWENT;	,
			IBM_TDB	
-	0	incompany means and means and management of the same and	USPAT;	2004/09/29
		pin same solder\$3	US-PGPUB; EPO; JPO;	13:28
			DERWENT;	
			IBM_TDB	2224/22/22
_	1	bifilar with winding same mounting with pin	USPAT; US-PGPUB;	2004/09/29
			EPO; JPO;	
			DERWENT;	
_	1	bifilar with winding same (solder	IBM_TDB USPAT;	2004/09/29
	_	soldering) with pin	US-PGPUB;	13:32
			EPO; JPO;	
		•	DERWENT; IBM TDB	
-	0	resistor adj wire same (solder soldering)	USPAT;	2004/09/29
		with pin	US-PGPUB;	13:32
			EPO; JPO; DERWENT;	
			IBM TDB	
	0	resistor\$3 adj wire same (solder	USPĀT;	2004/09/29
		soldering) with pin	US-PGPUB; EPO; JPO;	13:33
	•		DERWENT;	
			IBM_TDB	
-	985	resistor\$3 adj wire	USPAT;	2004/09/29
			US-PGPUB; EPO; JPO;	13:33
			DERWENT;	
	30	unnintanta	IBM_TDB	2004/00/20
-	30	resistor\$3 adj wire same (mounting mount)	USPAT; US-PGPUB;	2004/09/29
			EPO; JPO;	
			DERWENT;	
1	1	resistor\$3 adj wire same (mounting mount)	IBM_TDB USPAT;	2004/09/29
l _			,/	
_	1	same pin	US-PGPUB;	13:34
-			EPO; JPO;	13:34
_	1			13:34

Γ	589	resistor\$3 same (mounting mount) same	USPAT;	2004/09/29
-	369	pin	US-PGPUB;	13:34
		•	EPO; JPO;	
			DERWENT;	
	164		IBM_TDB	2004/00/20
-	464	resistor same (mounting mount) same pin	USPAT; US-PGPUB;	2004/09/29
			EPO; JPO;	15.54
			DERWENT;	
			IBM_TDB	
- ·	112	resistor with (mounting mount) with pin	USPAT;	2004/09/29
		,	US-PGPUB;	13:34
			EPO; JPO; DERWENT;	
			IBM TDB	
-	13	inrush with protection with induct\$5	USPĀT;	2004/09/29
	İ		US-PGPUB;	15:12
			EPO; JPO;	1
		•	DERWENT; IBM TDB	
_	228	(inrush transient) with protection with	USPAT;	2004/09/29
		induct\$5	US-PGPUB;	15:13
			EPO; JPO;	
			DERWENT;	
	4	(inrush transient) with protection with	IBM_TDB USPAT;	2004/09/29
_	4	induct\$5 and bifilar	US-PGPUB;	15:48
		Inducty's and billiar	EPO; JPO;	100
			DERWENT;	
		•	IBM_TDB	
-	413	induct\$5 with bifilar	USPAT;	2004/09/29
			US-PGPUB; EPO; JPO;	15:48
			DERWENT;	
			IBM TDB	
-	167	induct\$5 with bifilar near winding	USPAT;	2004/09/30
			US-PGPUB; EPO; JPO;	.09:5.4
	1		DERWENT;	
	1		IBM TDB	
-	1	de-20119996-\$.did.	USPAT;	2004/09/30
		·	US-PGPUB;	09:55
			EPO; JPO; DERWENT;	
			IBM TDB	
-	1	2002-373299	USPAT;	2004/09/30
			US-PGPUB;	10:32
			EPO; JPO;	
			DERWENT;	
_	6	("5118363"	USPAT;	2004/09/30
	1	"3851290"	US-PGPUB;	10:33
		"1641115").pn.	EPO; JPO;	
			DERWENT;	
_	6	("6118363"	IBM_TDB USPAT;	2004/09/30
		"3851290"	US-PGPUB;	10:36
		"1641115").pn.	EPO; JPO;	
	1	·	DERWENT;	
_	7	("6118363"	IBM_TDB USPAT;	2004/09/30
_	/	(~6118363~ "3851290"	US-PGPUB;	10:39
	["4641115").pn.	EPO; JPO;	
			DERWENT;	
		(4: 057, 774	IBM_TDB	2004/00/20
-	4	(4,057,774 3,573,676).pn.	USPAT; US-PGPUB;	2004/09/30
		3,373,070,.pm.	EPO; JPO;	11.30
			DERWENT;	
İ			IBM TDB	1

-	125	inrush same inductance	USPAT;	2004/09/30
			US-PGPUB;	11:37
			EPO; JPO;	
			DERWENT; IBM TDB	
_	27	inrush same inductance same transient	USPAT;	2004/09/30
	""		US-PGPUB;	12:46
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	542	inrush with power adj supply	USPĀT;	2004/09/30
			US-PGPUB;	12:48
			EPO; JPO;	
			DERWENT;	
_	0	inrush with power adj supply with	IBM_TDB USPAT;	2004/09/30
_	· ·	inductance	US-PGPUB;	12:49
			EPO; JPO;	20.15
		•	DERWENT;	
]		IBM TDB	
-	6	inrush with power adj supply same	USPAT;	2004/09/30
	1	inductance	US-PGPUB;	13:08
			EPO; JPO;	
			DERWENT;	
	1	/_3	IBM_TDB	2004/00/20
-	114	(electromagnetic adj compatibility) same induct\$5	USPAT; US-PGPUB;	2004/09/30
	ĺ	Inductas	EPO; JPO;	13:47
			DERWENT;	
		·	IBM TDB	
_	16	(electromagnetic adj compatibility) same	EPO;	2004/09/30
		induct\$5	DERWENT	13:26
-	10	(electromagnetic adj compatibility) same	USPAT;	2004/09/30
		low near induct\$5	US-PGPUB;	14:21
			EPO; JPO;	
			DERWENT;	
	81	(crosstalk cross-talk emc) same (inductor	IBM_TDB_ USPAT;	2004/09/30
_	01	inductance) near low	US-PGPUB;	14:57
		Inductance, near tow	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	8	(crosstalk cross-talk emc) same (inductor	EPO; JPO;	2004/09/30
		inductance) near low	DERWENT	14:24
_	3	(crosstalk cross-talk emc) same (inductor	EPO; JPO;	2004/09/30
		inductance) near (power near (supply	DERWENT	14:45
_	1	source)) (crosstalk cross-talk emc) same (inductor	USPAT;	2004/09/30
	1	inductance) near (power near (supply	EPO; JPO;	14:42
	1	source)) and 6483714.pn.	DERWENT	
-	6	6483714.pn.	USPAT;	2004/09/30
		•	EPO; JPO;	14:43
			DERWENT	
-	10	(crosstalk cross-talk emc) same (inductor	USPAT;	2004/09/30
		inductance) near (power near (supply	US-PGPUB;	14:50
		source))	EPO; JPO;	
_	8	(crosstalk cross-talk emc) same (inductor	DERWENT USPAT;	2004/09/30
1 -	· ·	inductance) near2 power adj supply	US-PGPUB;	14:58
		Inductance, nears power adj suppry	EPO; JPO;	11.50
			DERWENT;	
			IBM_TDB	
-	509	coil with winding with insulated adj wire	USPĀT;	2004/10/01
			US-PGPUB;	14:00
			EPO; JPO;	
			DERWENT;	
I	1	I	IBM TDB	i i

			140000 10004/10/01
_	0	coil with winding with insulated adj wire with cupper	USPAT; 2004/10/01 US-PGPUB; 14:01
		with cupper	EPO; JPO;
			DERWENT;
			IBM TDB
_	18	coil with winding with insulated adj wire	1 1
		with copper	US-PGPUB; 14:05
		_ 	EPO; JPO;
			DERWENT;
			IBM_TDB
-	149785	coil with winding wire with copper	USPAT; 2004/10/01
			US-PGPUB; 14:05 EPO; JPO;
			DERWENT;
			IBM TDB
-	1330	coil with winding with wire with copper	USPAT; 2004/10/01
		1	US-PGPUB; 14:05
			EPO; JPO;
			DERWENT;
			IBM_TDB
-	10		USPAT; 2004/10/01
		same bifilar	US-PGPUB; 14:12 EPO; JPO;
		j	DERWENT;
			IBM TDB
-	0	coil with winding with wire with copper	USPAT; 2004/10/01
		same bifilar same space	US-PGPUB; 14:13
			EPO; JPO;
			DERWENT;
			IBM_TDB
-	0	coil with winding with wire with copper same bifilar same spaced	US-PGPUB; 14:13
ļ		Same Dilital Same Spaced	EPO; JPO;
İ			DERWENT;
			IBM TDB
-	3		USPAT; 2004/10/01
		same insulation same spaced	US-PGPUB; 14:21
		<u> </u>	1
			EPO; JPO;
			DERWENT;
_	103		DERWENT; IBM_TDB
_	103	coil with winding with wire with copper	DERWENT; IBM_TDB USPAT; 2004/10/01
_	103		DERWENT; IBM_TDB USPAT; 2004/10/01
_	103	coil with winding with wire with copper	DERWENT; IBM_TDB USPAT; 2004/10/01 US-PGPUB; 14:21
_		coil with winding with wire with copper near insulat\$3	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
-		coil with winding with wire with copper near insulat\$3	DERWENT; IBM_TDB USPAT; 2004/10/01 US-PGPUB; 14:21 EPO; JPO; DERWENT; IBM_TDB USPAT; 2004/10/01
-		coil with winding with wire with copper near insulat\$3	DERWENT; IBM_TDB USPAT; 2004/10/01 US-PGPUB; 14:21 EPO; JPO; DERWENT; IBM_TDB USPAT; 2004/10/01 US-PGPUB; 14:22
_		coil with winding with wire with copper near insulat\$3	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; 14:21 2004/10/01 14:22 EPO; JPO;
-		coil with winding with wire with copper near insulat\$3	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; COMMOND IN CO
-	123	coil with winding with wire with copper near insulat\$3	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; 14:21 2004/10/01 14:22 EPO; JPO;
-	123	coil with winding with wire with copper near insulat\$3 coil with winding with wire near copper near insulat\$3	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;
-	123	coil with winding with wire with copper near insulat\$3 coil with winding with wire near copper near insulat\$3 coil with winding with copper adj wire	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; IA:22 EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; IA:23 EPO; JPO;
-	123	coil with winding with wire with copper near insulat\$3 coil with winding with wire near copper near insulat\$3 coil with winding with copper adj wire	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;
-	123 119	coil with winding with wire with copper near insulat\$3 coil with winding with wire near copper near insulat\$3 coil with winding with copper adj wire near insulat\$3	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; I4:22 EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
-	123 119	coil with winding with wire with copper near insulat\$3 coil with winding with wire near copper near insulat\$3 coil with winding with copper adj wire near insulat\$3 coil near winding with copper adj wire	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; I4:22 EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; 2004/10/01
_	123 119	coil with winding with wire with copper near insulat\$3 coil with winding with wire near copper near insulat\$3 coil with winding with copper adj wire near insulat\$3	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; 14:23 EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; 14:23 EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; 14:24
-	123 119	coil with winding with wire with copper near insulat\$3 coil with winding with wire near copper near insulat\$3 coil with winding with copper adj wire near insulat\$3 coil near winding with copper adj wire	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; I4:22 EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; 2004/10/01
	123 119 38	coil with winding near insulat\$3 coil with winding near insulat\$3 coil with winding near insulat\$3 coil with winding near insulat\$3 coil near winding near insulat\$3	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
	123 119	coil with winding near insulat\$3 coil with winding near insulat\$3 coil with winding near insulat\$3 coil with winding near insulat\$3 coil near winding near insulat\$3 coil near winding with copper adj wire near insulat\$3	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; USPAT; US-QU4/10/01
	123 119 38	coil with winding near insulat\$3 coil with winding near insulat\$3 coil with winding near insulat\$3 coil with winding near insulat\$3 coil near winding near insulat\$3	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; I4:24
	123 119 38	coil with winding near insulat\$3 coil with winding near insulat\$3 coil with winding near insulat\$3 coil with winding near insulat\$3 coil near winding near insulat\$3 coil near winding with copper adj wire near insulat\$3	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; I4:24 EPO; JPO;
	123 119 38	coil with winding near insulat\$3 coil with winding near insulat\$3 coil with winding near insulat\$3 coil with winding near insulat\$3 coil near winding near insulat\$3 coil near winding with copper adj wire near insulat\$3	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;
	123 119 38	coil with winding with wire with copper near insulat\$3 coil with winding with wire near copper near insulat\$3 coil with winding with copper adj wire near insulat\$3 coil near winding with copper adj wire near insulat\$3 coil near winding with copper adj wire near insulat\$3	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; I4:24 EPO; JPO;
-	123 119 38 7641	coil with winding near insulat\$3 coil with winding with wire near copper near insulat\$3 coil with winding with copper adj wire near insulat\$3 coil near winding with copper adj wire near insulat\$3 coil near winding with copper adj wire near insulat\$3	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
	123 119 38 7641	coil with winding with wire with copper near insulat\$3 coil with winding with wire near copper near insulat\$3 coil with winding with copper adj wire near insulat\$3 coil near winding with copper adj wire near insulat\$3 coil near winding with copper adj wire near insulat\$3 adn bifilar	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;
	123 119 38 7641	coil with winding with wire with copper near insulat\$3 coil with winding with wire near copper near insulat\$3 coil with winding with copper adj wire near insulat\$3 coil near winding with copper adj wire near insulat\$3 coil near winding with copper adj wire near insulat\$3 adn bifilar	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; I4:24

_	0	coil near winding with copper with wire near insulat\$3 and bifilar	USPAT; US-PGPUB; EPO; JPO;	2004/10/01 14:25
			DERWENT; IBM TDB	
-	1	coil near winding with copper with wire with insulat\$3 and bifilar	USPAT; US-PGPUB;	2004/10/01 14:26
			EPO; JPO; DERWENT;	
	0	coil near winding with copper with wire	IBM_TDB USPAT;	2004/10/01
		with insulat\$3 same bifilar	US-PGPUB; EPO; JPO;	14:26
			DERWENT; IBM TDB	
-	11	winding with copper with wire with insulat\$3 same bifilar	USPAT; US-PGPUB;	2004/10/01 15:32
			EPO; JPO; DERWENT;	
_	14013	winding with spaced	IBM_TDB USPAT;	2004/10/01
		• • •	US-PGPUB; EPO; JPO;	15:32
			DERWENT; IBM_TDB	
-	.0	winding with spaced with wire with appart	USPAT; US-PGPUB;	2004/10/01 15:33
			EPO; JPO; DERWENT;	-
_	411	winding with spaced with wire with	IBM_TDB USPAT;	2004/10/01
		apart	US-PGPUB; EPO; JPO;	15:33
			DERWENT;	
-	140	coil with winding with spaced with wire with apart	USPAT; US-PGPUB;	2004/10/01 15:34
	<u>-</u>		EPO; JPO; DERWENT;	
-	2		IBM_TDB USPAT;	2004/10/01
	_	with apart with insulation	US-PGPUB; EPO; JPO;	15:35
			DERWENT; IBM TDB	
-	4	winding with spaced with wire with apart with insulation	USPAT; US-PGPUB;	2004/10/01 15:36
			EPO; JPO; DERWENT;	
_	40	winding with spaced with wire with	IBM_TDB USPAT;	2004/10/01
	· · · · · · · · · · · · · · · · · · ·	insulation	US-PGPUB; EPO; JPO;	15:38
			DERWENT; IBM_TDB	
<i>-</i>	12	winding with spaced with wire with bare	USPAT; US-PGPUB;	2004/10/01 15:40
			EPO; JPO; DERWENT;	
-	25	coil with spaced with wire with bare	IBM_TDB USPAT;	2004/10/01
		·	US-PGPUB; EPO; JPO;	15:40
			DERWENT; IBM_TDB	
-	55	integrated adj circuit with pin near soldered	USPAT; US-PGPUB;	2004/10/04 16:38
			EPO; JPO; DERWENT;	
<u> </u>			IBM_TDB	

-	1	integrated adj circuit with terminal adj	USPAT;	2004/10/04
		pin near soldered	US-PGPUB;	16:39
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	2004/10/04
_	55	integrated adj circuit with pin near soldered	USPAT;	2004/10/04 16:45
	İ	soldered	US-PGPUB; EPO; JPO;	10:45
		·	DERWENT;	
			IBM TDB	
_	. 649	circuit with (wire adj end pin) near	USPAT;	2004/10/04
	043	soldered	US-PGPUB;	16:46
		Jordered	EPO; JPO;	10.10
			DERWENT;	
			IBM TDB	
-	0	circuit with (wire adj end pin) near	USPAT;	2004/10/04
		soldered with prinded near circuit adj	US-PGPUB;	16:47
		board	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	(wire adj end pin) near soldered with	USPAT;	2004/10/04
		prinded near circuit adj board	US-PGPUB;	16:47
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	(wire pin) near soldered with prinded	USPAT;	2004/10/04
		near circuit adj board	US-PGPUB;	16:47
			EPO; JPO;	1
			DERWENT; IBM TDB	,
]	446	(wire pin) near soldered with printed	USPAT;	2004/10/04
-	440	near circuit adj board	US-PGPUB;	16:47
		Hear Circuit adj board	EPO; JPO;	10.17
			DERWENT;	
	İ		IBM TDB	
_	281	circuit with (wire adj end pin) near	USPĀT;	2004/10/04
]	soldered with printed near circuit adj	US-PGPUB;	16:48
		board	EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	
-	5	circuit with (wire adj end termibal adj	USPAT;	2004/10/04
		pin) near soldered with printed near	US-PGPUB;	16:50
		circuit adj board	EPO; JPO;	
			DERWENT;	
		circuit with (termibal adj pin) near	IBM_TDB USPAT;	2004/10/04
-		soldered with printed near circuit adj	US-PGPUB;	16:50
		board	EPO; JPO;	10.00
		20024	DERWENT;	
			IBM TDB	
-	27	circuit with (terminal adj pin) near	USPAT;	2004/10/07
		soldered with printed near circuit adj	US-PGPUB;	09:58
		board	EPO; JPO;	
1			DERWENT;	
			IBM_TDB	
-	2		USPAT;	2004/10/04
		soldered with printed near circuit adj	US-PGPUB;	16:55
		board with wire	EPO; JPO;	
			DERWENT;	
1 '			IBM TDB	į i